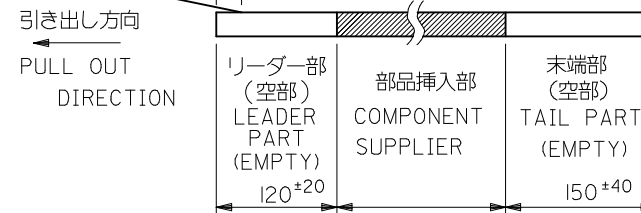
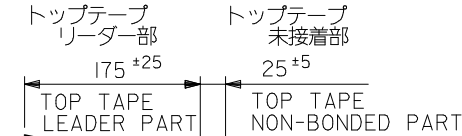


注記 NOTES

1. 製品番号 52746-***39 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面 SD-52746-025 を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52746-***39 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52746-025

2. 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)

0.1N ~ 1.3N { 10gf ~ 130gf }

尚、本規格値は、出荷時に適用。

(但し、輸送時に剥離が発生しない事。)

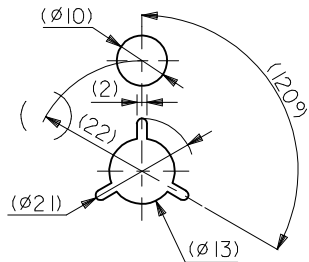
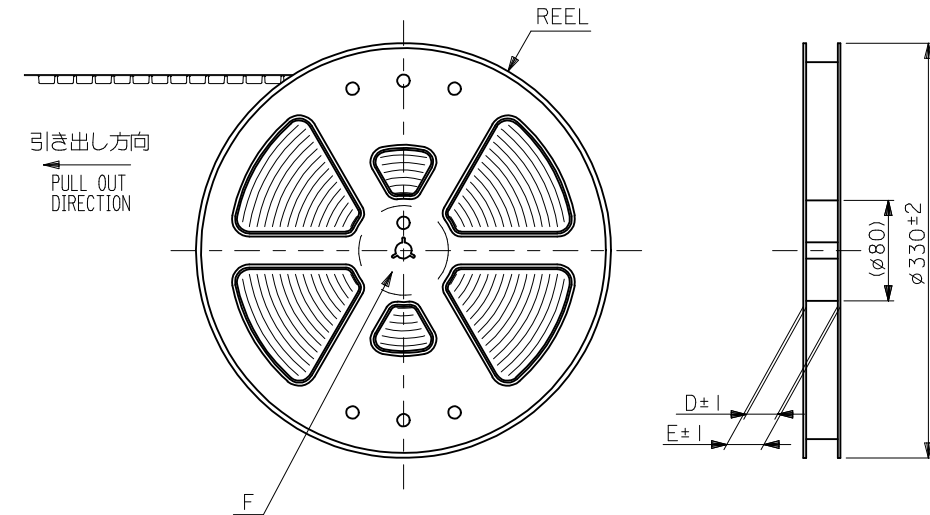
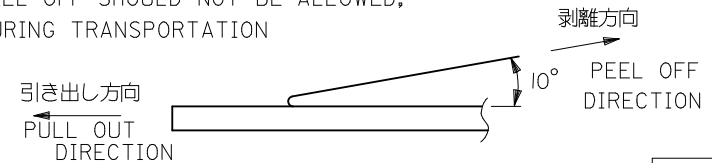
PEELING OFF FORCE OF TOP TAPE

0.1N ~ 1.3N { 10gf ~ 130gf } (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)

THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT

PEEL OFF SHOULD NOT BE ALLOWED,

DURING TRANSPORTATION



DETAIL F

5. 材料
キャリアテープ:ポリプロピレン (PP)
トップテープ:PET, PE, PEF
リール:ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は 52746-***81 の鉛フリー品です

THIS PRODUCT IS LEAD FREE OF 52746-***81

7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。

THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

MODEL No.52746-***71

REVISED EC NO: J2009-2061 DRWN:TKON CHKD:HMATSUMOTO APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN ZIF SMT RA B/CONT EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/01/30					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE '04/01/30	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2.3		SD-52746-024		1 OF 3		
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

F

E

D

C

B

A

F

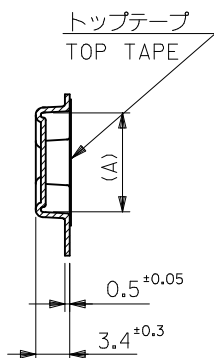
E

D

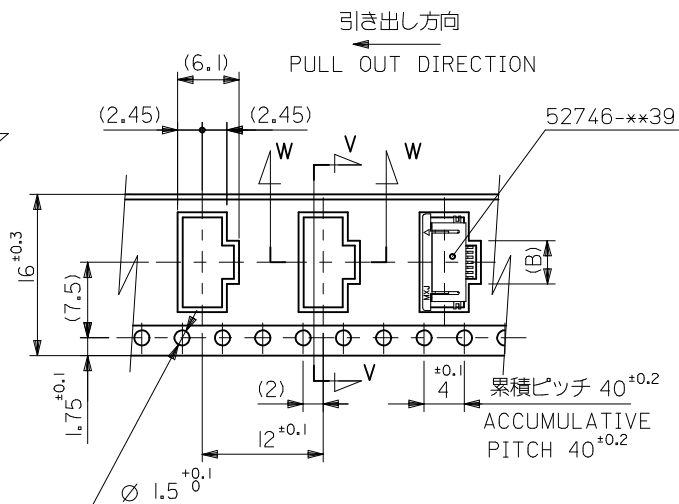
C

B

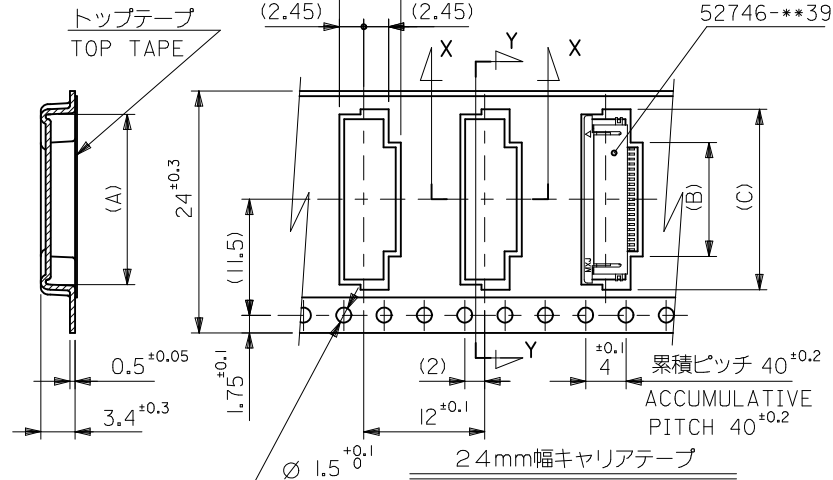
A



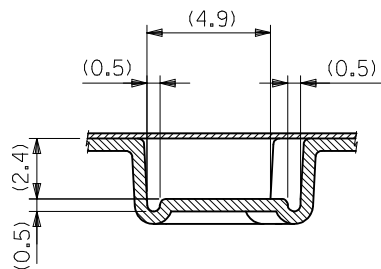
SECT.V-V



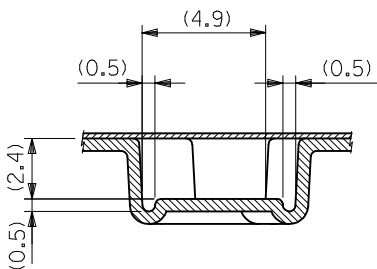
16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE



SECT.Y-Y



SECT. W-W



SECT.X-X

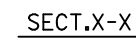
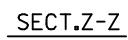
24	29.4	25.4	24.4	11.8	17.4	52746-2271	22		
			17.9	11.3	16.9	52746-2171	21		
			17.4	10.8	16.4	52746-2071	20		
			16.9	10.3	15.9	52746-1971	19		
			16.4	9.8	15.4	52746-1871	18		
			15.9	9.3	14.9	52746-1771	17		
			15.4	8.8	14.4	52746-1671	16		
			14.9	8.3	13.9	52746-1571	15		
			14.4	7.8	13.4	52746-1471	14		
			13.9	7.3	12.9	52746-1371	13		
			13.4	6.8	12.4	52746-1271	12		
			12.9	6.3	11.9	52746-1171	11		
			12.4	5.8	11.4	52746-1071	10		
			11.9	5.3	10.9	52746-0971	9		
			11.4	4.8	10.4	52746-0871	8		
16	21.4	17.4	10.9	4.3	9.9	52746-0771	7		
			10.4	3.8	9.4	52746-0671	6		
			9.4	2.8	8.4	52746-0471	4		
キャリアテープ幅 CARRIER TAPE WIDTH			E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

REVISED
EC NO: J2009-2061
DRWN:TKN
CHKD:HMATSUMOTO
APPR:NUK ITA
2009/05/20
2009/05/21
2009/05/21

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
HS HIMABUKURO	'04/01/30
CHECKED BY	DATE
KTOJO	'04/01/30
APPROVED BY	DATE
MSASAO	'04/01/30
MATERIAL NO.	
SEE TABLE	
SIZE A3	

SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 0.5 FPC CONN ZIF SMT RA B/CONT EMBSTP PKG -LEAD FREE-		
MOLEX INCORPORATED		
DOCUMENT NO. SD-52746-024		SHEET NO. 2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



MODEL No.52746-xx71

tb_frame_A3_J_ME_S
Rev. E 2006/04/15

注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、茶色
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN
ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
金具: リン青銅、ニッケル下地金めっき (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52746-xx39 SHOULD BE LOCKED.

3.ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、

基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.

UPPER DIRECTION: 0.1MAXIMUM

LOWER DIRECTION: 0.15 MAXIMUM

4.偶数極に適用

APPLY FOR EVEN CIRCUIT.

5.ハ' ターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6.R0.3は、FPCの導体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7.ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打ち抜き方向は導体側から補強板を推奨いたします。

補強フィルム材質はポリイミドを推奨いたします。

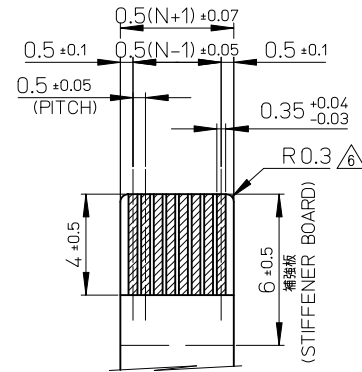
ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFNER BOARD SIDE.

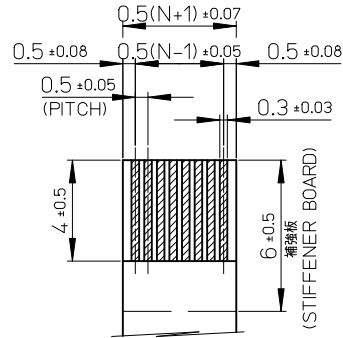
RECOMMENDED MATERIAL:

STIFFNER FILM: POLYIMIDE

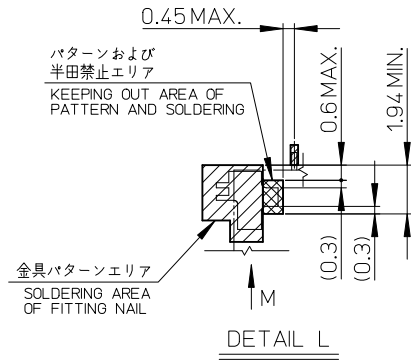
BONDING AGENT: THERMOSETTING BONDING AGENT



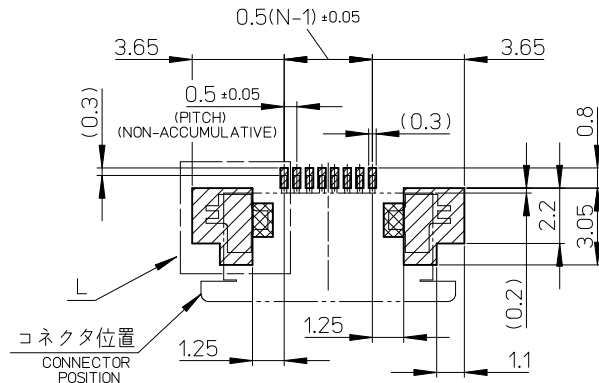
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3+0.03/-0.03



適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3+0.03/-0.03

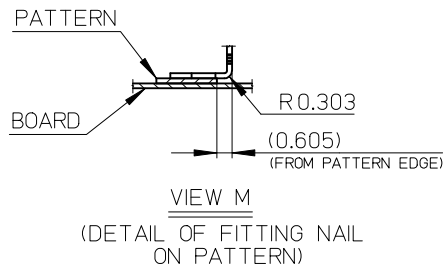


DETAIL L



参考基板レイアウト (マウント面)

RECOMMENDED P.C.BOARD
PATTERN DIMENSION(REF.)
(MOUNTING SIDE)



VIEW M
(DETAIL OF FITTING NAIL
ON PATTERN)

REVISED	EC NO.: J2011-0041 DRAWN: HAYASHI NO CHKD: HIRAJIMA APPR: KIMORI KAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			10 UNDER	± ---	DRAWN BY HSHIMABUKURO	DATE '04/01/30	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) GOLD PLATING				
			10 OVER 30 UNDER	± ---	CHECKED BY KTOJO	DATE '04/01/30					
			30 OVER	± ---	APPROVED BY MSASAO	DATE '04/01/30					
			ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52746-025		2 OF 2		
			REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							